



PRODUCT DATA SHEET



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Datasheet



Resources



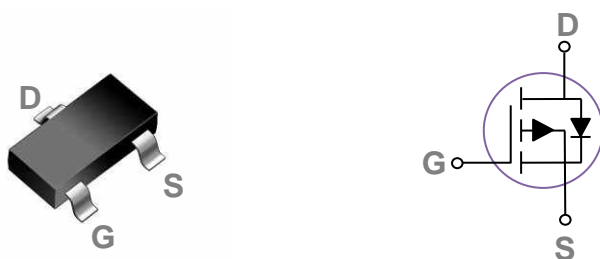
Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOT23-3 Pin Configuration



BVDSS	RDSON	ID
-30V	20mΩ	-9A

Features

- -30V, -9A, $R_{DS(ON)} = 20m\Omega @ V_{GS} = -10V$
- Fast switching
- Green Device Available
- Suit for -4.5V Gate Drive Applications

Applications

- MB / VGA / Vcore
- POL Applications
- Load Switch
- LED Application

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_A=25^\circ\text{C}$)	-9.0	A
	Drain Current – Continuous ($T_A=70^\circ\text{C}$)	-4.4	A
I_{DM}	Drain Current – Pulsed ¹	-22	A
P_D	Power Dissipation ($T_A=25^\circ\text{C}$)	1.25	W
	Power Dissipation – Derate above 25°C	0.01	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	100	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=-250\mu A$	-30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=-1\text{mA}$	---	-0.03	---	V/ $^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-30V$, $V_{GS}=0V$, $T_J=25^{\circ}\text{C}$	---	---	-1	μA
		$V_{DS}=-24V$, $V_{GS}=0V$, $T_J=125^{\circ}\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$	---	---	± 100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-10V$, $I_D=-4A$	---	20	25	$m\Omega$
		$V_{GS}=-4.5V$, $I_D=-2A$	---	26	36	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu A$	-1.0	-1.6	-2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	4	---	$mV/^{\circ}\text{C}$
g_{fs}	Forward Transconductance	$V_{DS}=-10V$, $I_D=-3A$	---	6.8	---	S

Dynamic and switching Characteristics

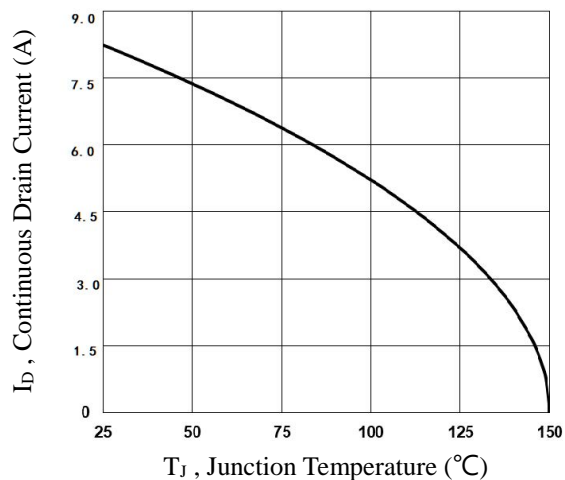
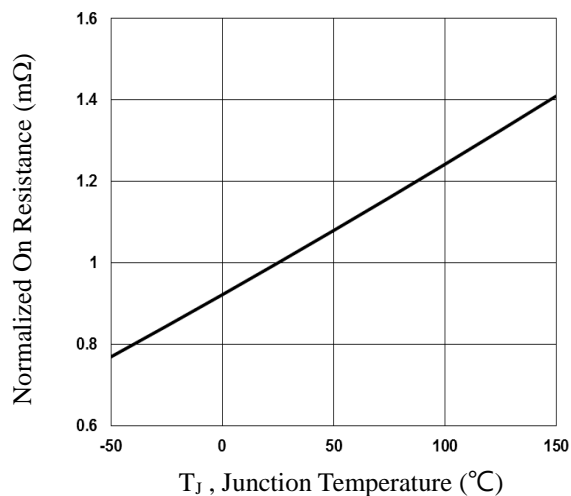
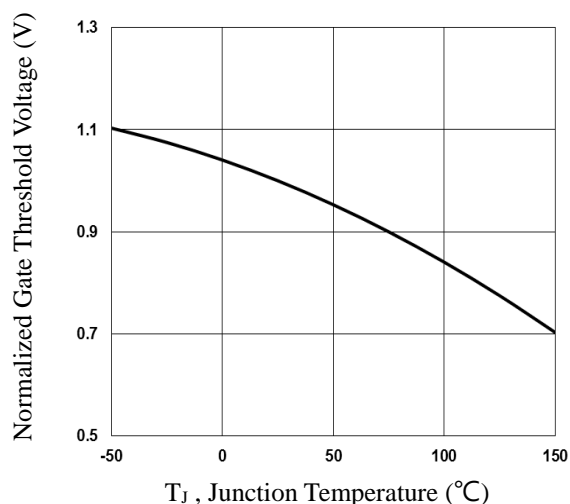
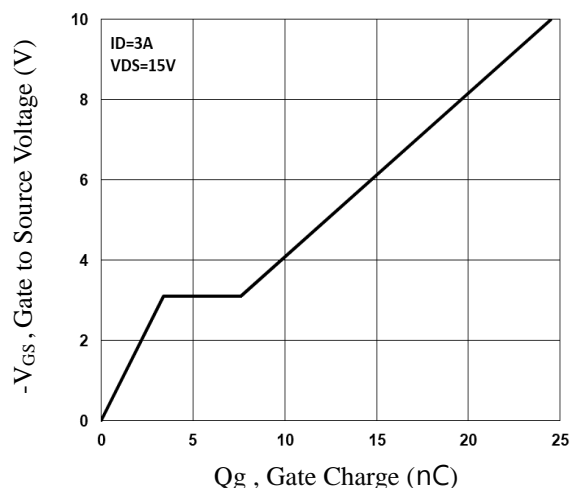
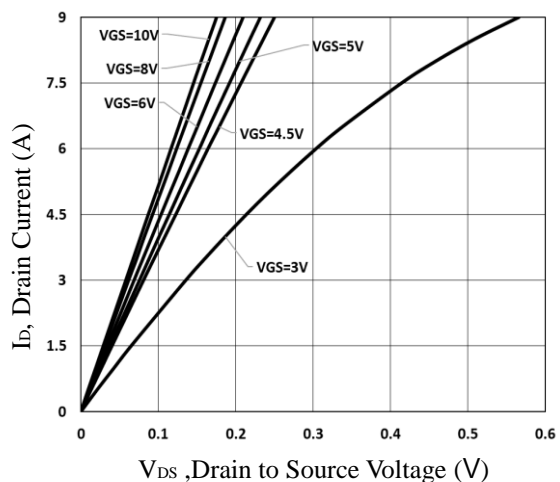
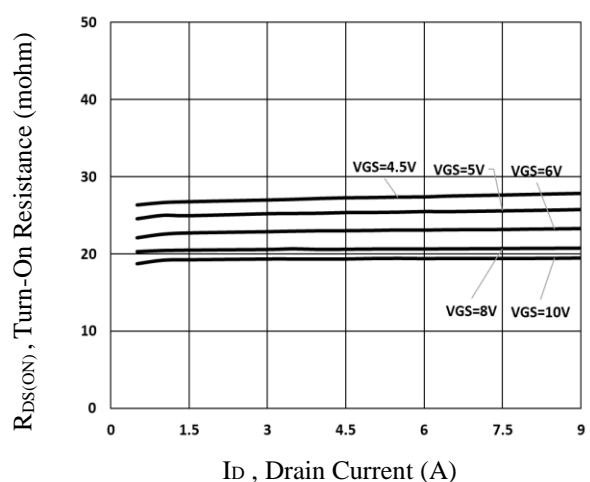
Q_g	Total Gate Charge ^{2, 3}	$V_{DS}=-15V$, $V_{GS}=-10V$, $I_D=-3A$	---	24.5		nC
Q_{gs}	Gate-Source Charge ^{2, 3}		---	3.4		
Q_{gd}	Gate-Drain Charge ^{2, 3}		---	4.2		
$T_{d(on)}$	Turn-On Delay Time ^{2, 3}	$V_{DD}=-15V$, $V_{GS}=-10V$, $R_G=6\Omega$ $I_D=-1A$	---	5.8		ns
T_r	Rise Time ^{2, 3}		---	18.8		
$T_{d(off)}$	Turn-Off Delay Time ^{2, 3}		---	46.9		
T_f	Fall Time ^{2, 3}		---	12.3		
C_{iss}	Input Capacitance	$V_{DS}=-15V$, $V_{GS}=0V$, $F=1\text{MHz}$	---	1250		pF
C_{oss}	Output Capacitance		---	160		
C_{rss}	Reverse Transfer Capacitance		---	90		

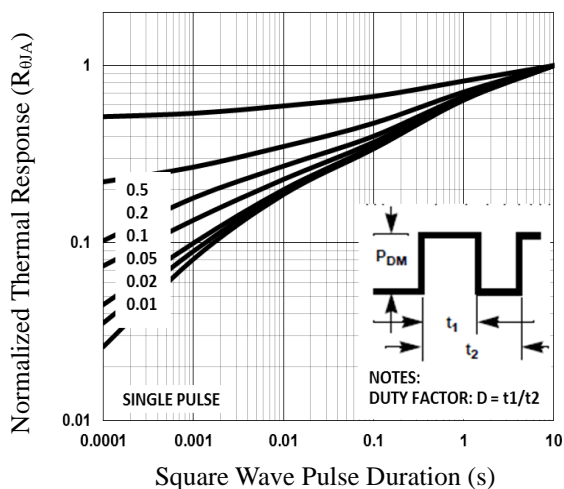
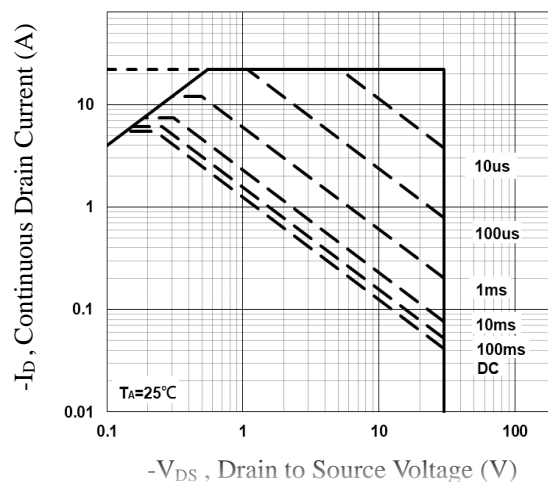
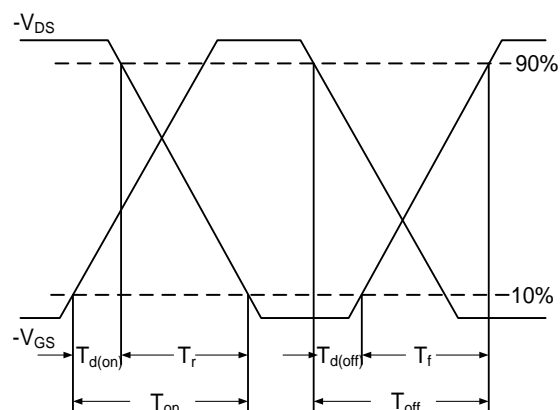
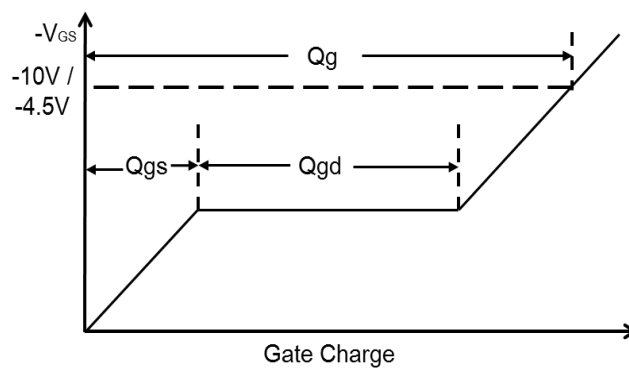
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	-9	A
I_{SM}	Pulsed Source Current		---	---	-11	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V$, $I_S=-1A$, $T_J=25^{\circ}\text{C}$	---	---	-1.2	V

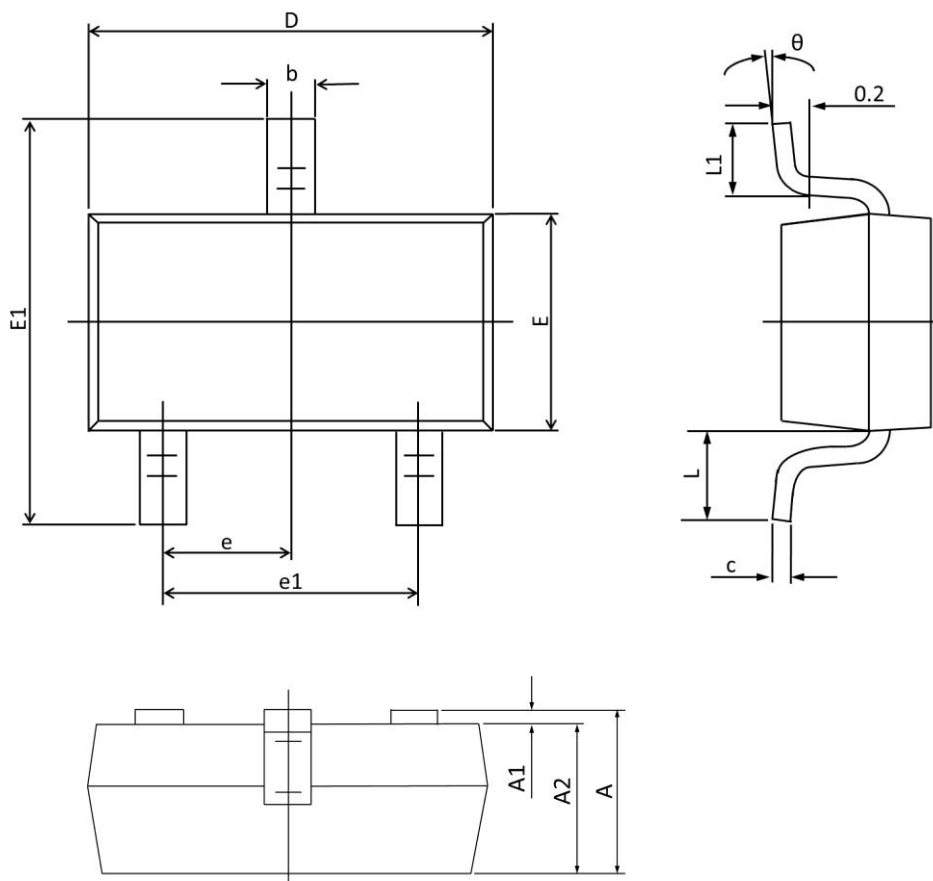
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_J

Fig.2 Normalized R_{DS(on)} vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Typical Output Characteristics

Fig.6 Turn-On Resistance vs. I_D


Fig.7 Normalized Transient Impedance

Fig.8 Maximum Safe Operation Area

Fig.9 Switching Time Waveform

Fig.10 Gate Charge Waveform

SOT23-3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.400	0.012	0.016
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.700 REF.		0.028 REF.	
L1	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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